●WLP-6-05 Power Dissipation

Power dissipation data for the WLP-6-05 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: 40mm×40mm (1600mm^2 in one side

Metal Area: 1st Metal Layer about 50%

2nd Inner Metal Layer about 50%

3rd Inner Metal Layer about 50%

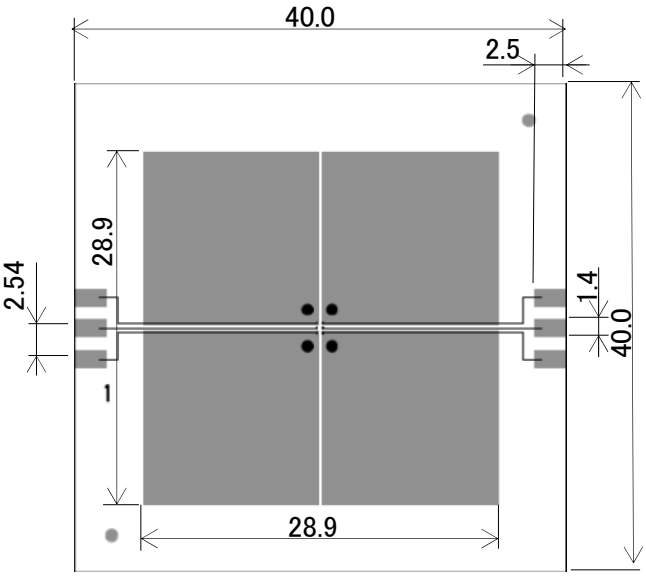
4th Metal Layer about 50%

Material: Glass Epoxy (FR-4)

Thickness: 1.6mm

Through-hole: 4 x 0.8 Diameter

Copper foil Thickness : Front-side 35um, Back-side 35um



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tj max=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)		θja(℃/W)
	Ta max=85℃	Ta max=105℃	
25	700	700	142.86
85	280	280	
105	0	140	
125	0	0